

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Shin-Chi Chen	06/12/2014
Chih-Yueh Li	06/19/2014
Shui-Yen Lu	06/19/2014
Chi-Mao Hsu	06/19/2014
Yuan-Chi Pai	06/19/2014
Yu-Hong Kuo	06/19/2014
Nien-Ting Ho	06/19/2014
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14314425
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NAME OF SUBMITTER:	ANNA SHILLINGBURG
SIGNATURE:	/Anna Shillingburg/
DATE SIGNED:	06/25/2014
This document serves as an Oath/Declaration (37 CFR 1.63).	

PATENT

Total Attachments: 4

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Serial No. _____
Attorney Docket No. _____
Ref. No. UMCD-2014-0096
Sundial Ref. No. US10680PA

Combined Declaration and Assignment for Patent Application

For the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE

I hereby declare that: As a below named inventor

The specification of which is attached hereto unless the following box is checked

☐ was filed on

as United States Application Number or PCT International Application Number

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that willful false statements made in this statement is punishable under 18 U.S.C. 1001 by fine or/and imprisonment of not more than five (5) years.

ASSIGNMENT

WHEREAS, I(we), the named inventor(s), whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR,

WHEREAS, **United Microelectronics Corp.**

whose post office address is **No3, Li-Hsin Rd.II, Hsinchu Science Park, Taiwan 30078, ROC.**

hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said invention and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part, and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Serial No. _____
Attorney Docket No. _____
Ref. No. USPCO-2014-0008
Serial Ref. No. US 10680PA

ALSO, Assignor hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said invention, including additional documents that may be required to effect the rights of Assignor in and to said invention, all without further consideration. Assignor also agrees, without further consideration and at Assignor's expense, to identify and communicate to Assignee at Assignee's request documents and information concerning the invention that are within Assignor's possession or control, and to provide further assurances and testimony on behalf of Assignor that lawfully may be required of Assignor in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. Assignor's obligations under this instrument shall extend to Assignor's heirs, executors, administrators and other legal representatives.

ALSO, Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to Assignee, as the Assignor of the entire right, title and interest in and to the same, for Assignor's sole use and behoof, and for the use and behoof of Assignor's legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made.

Legal Name of the Sole Or First Inventor			
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Serial No. _____
Attorney Docket No. _____
Ref. No. UMJD-2014-0088
Sundia Ref. No. LIS10500PA

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Pat. No. UMCD-2014-5905
Sunrise Ref. No. US100009A

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